

## PASSIVATED ASSEMBLED CIRCUIT ELEMENTS 50 A

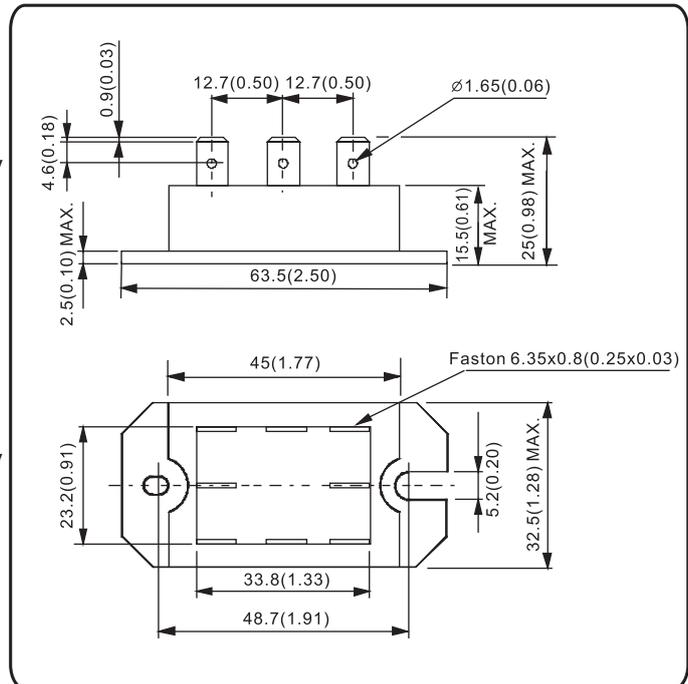
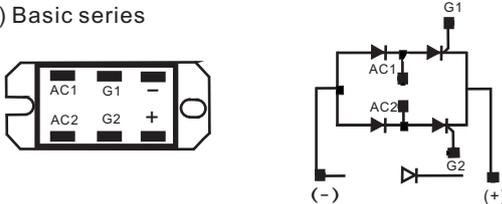
### Features

1. Electrically isolated base plate
2. Voltage rating up to 1600V
3. Glass passivated junctions for greater reliability
4. High dynamic characteristics
5. Simplified mechanical design and assembly
6. Wide choice of circuit configurations

Ordering code

<b>NP</b>	<b>50</b>	<b>5</b>	<b>W</b>
(1)	(2)	(3)	(4)

- (1) For Passivated Assembled Modules  
 (2) Maximum average forward current, A  
 (3) 1=400V : 2=800V : 3=1000V : 4=1200V : 5=1600V  
 (4) Basic series



### Electrical Characteristics

Parameter		Condition	Max. Value	Unit
$I_T(AV)$	Max. Average on-state current	180° half sine wave, 50 Hz Single side cooled, $T_C=85^\circ C$	50	A
$I_{FSM}$	Non-repetitive on-state or forward current	$t=10ms$	600	A
$V_{RRM}$ $V_{DRM}$	Max. repetitive peak reverse voltage		400 to 1600	V
$I_{RRM}$ $I_{DRM}$	Repetitive peak reverse current	$V_R = V_{RRM}$	10	mA
$I_{TSM}$	Max. peak, one-cycle, on-state non-repetitive surge current	$t=10ms$	715	A
$I_t^2$	Max. Permissible surge energy		900	A <sup>2</sup> S
$V_{TM}$	Max. Forward voltage drop		1.4	V
$V_{T(TO)}$	Value of threshold voltage		0.83	V
$r_{t1}$	On-state slope resistance		9.61	m $\Omega$
$I_{GD}$	Max. Required DC gate current to trigger	$T_j=25^\circ C$	60	mA
$V_{GT}$	Max. Required DC gate voltage to trigger		2	V
$I_H$	Max. Holding current		130	mA
$V_{GD}$	Max. Gate voltage which will not trigger any devices	At 67% $V_{DRM}$	0.20	V
$dv/dt$	Critical rate of rise of off-state voltage	$V_{DM} = 0.67 V_{DRM}$	200	V/us
$di/dt$	Max. Rate of rise of turned-on current	Gate drive 20V, 20 $\Omega$ , $t_r \leq 0.5 us$	200	A/us
$T_{stg}$	Storage temperature range		-40 to 125	$^\circ C$
$R_{th(J-C)}$	Max. Thermal resistance	Single side cooled	1.05	K/W
$W_t$	Approximate weight		58	g
T	Module to heatsink ( M 6 )	A mounting compound is recommended. Torque should be rechecked after a period of 3 hours.	4	Nm

